



DRA2L14Y0L

Silicon PNP epitaxial planar type

For digital circuits

■ Features

- High forward current transfer ratio hFE
- Low collector-emitter saturation voltage Vce(sat)
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

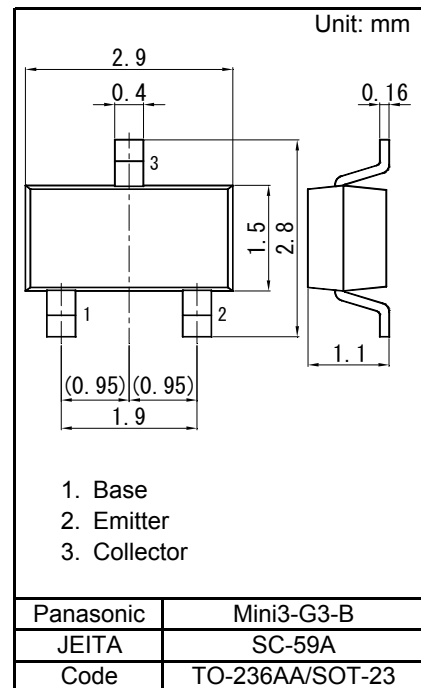
■ Marking Symbol: K4

■ Packaging

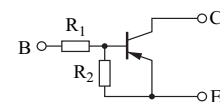
Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	VCBO	-30	V
Collector-emitter voltage (Base open)	VCEO	-30	V
Collector current	IC	-100	mA
Total power dissipation	PT	200	mW
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C



Internal Connection



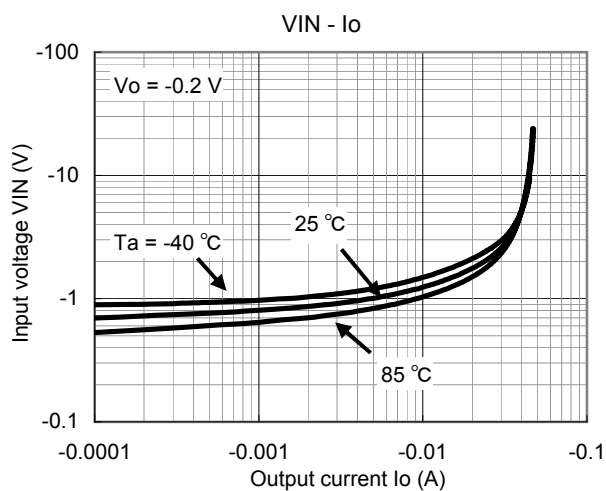
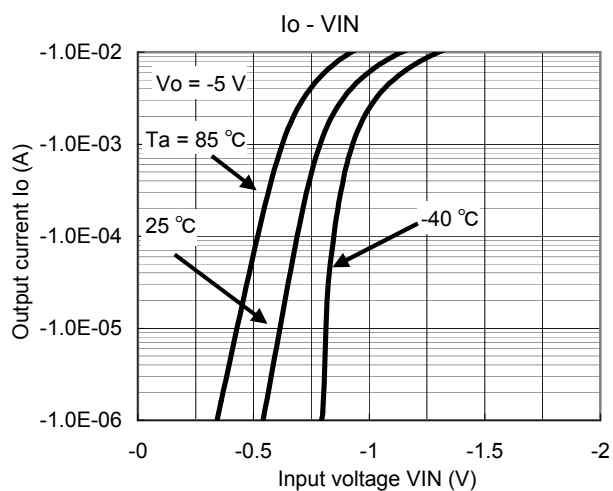
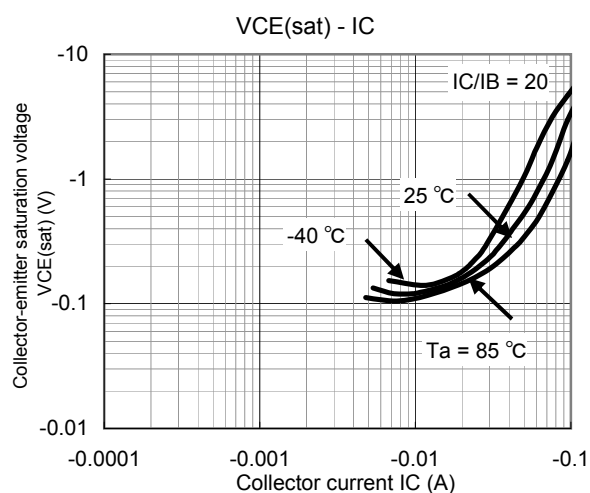
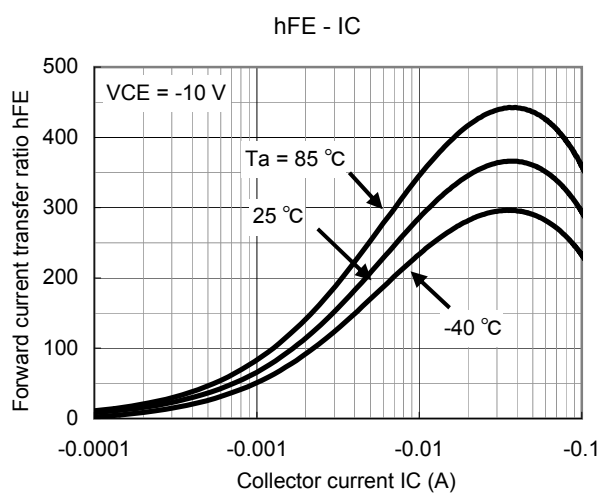
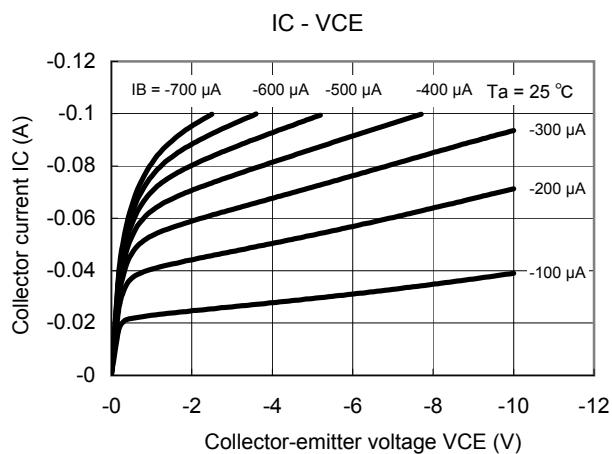
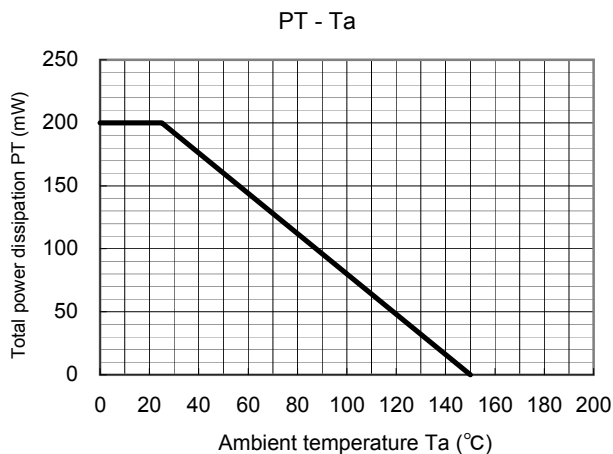
Resistance value	R1	R2	Unit
	10	47	kΩ

■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	VCBO	IC = -10 μA, IE = 0	-30			V
Collector-emitter voltage (Base open)	VCEO	IC = -2 mA, IB = 0	-30			V
Collector-base cutoff current (Emitter open)	ICBO	VCB = -30 V, IE = 0			-0.1	μA
Collector-emitter cutoff current (Base open)	ICEO	VCE = -30 V, IB = 0			-0.5	μA
Emitter-base cutoff current (Collector open)	IEBO	VEB = -3 V, IC = 0			-0.1	mA
Forward current transfer ratio	hFE	VCE = -10 V, IC = -5 mA	80			-
Collector-emitter saturation voltage	VCE(sat)	IC = -50 mA, IB = -0.33 mA		-0.6	-1.2	V
Input voltage	Vi(on)	VCE = -0.2 V, IC = -5 mA	-1.5			V
	Vi(off)	VCE = -5 V, IC = -100 μA			-0.5	V
Input resistance	R1		-30%	10	+30%	kΩ
Resistance ratio	R1/R2		0.16	0.213	0.27	-

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 Measuring methods for transistors.

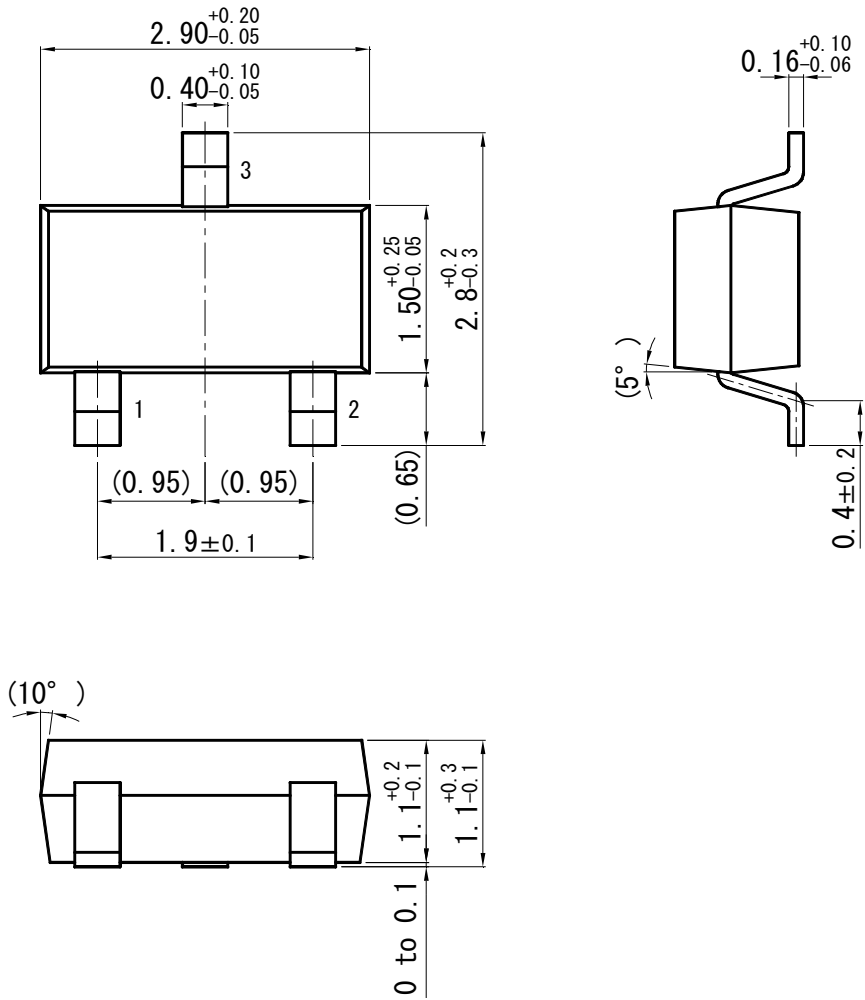
Technical Data (reference)



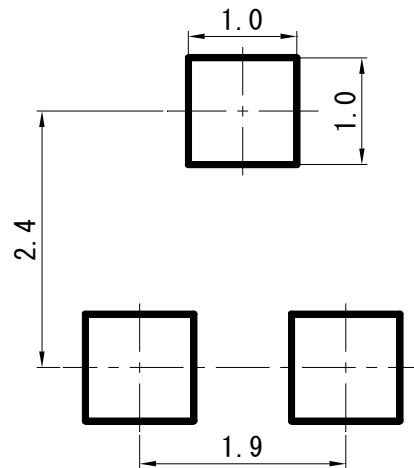


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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